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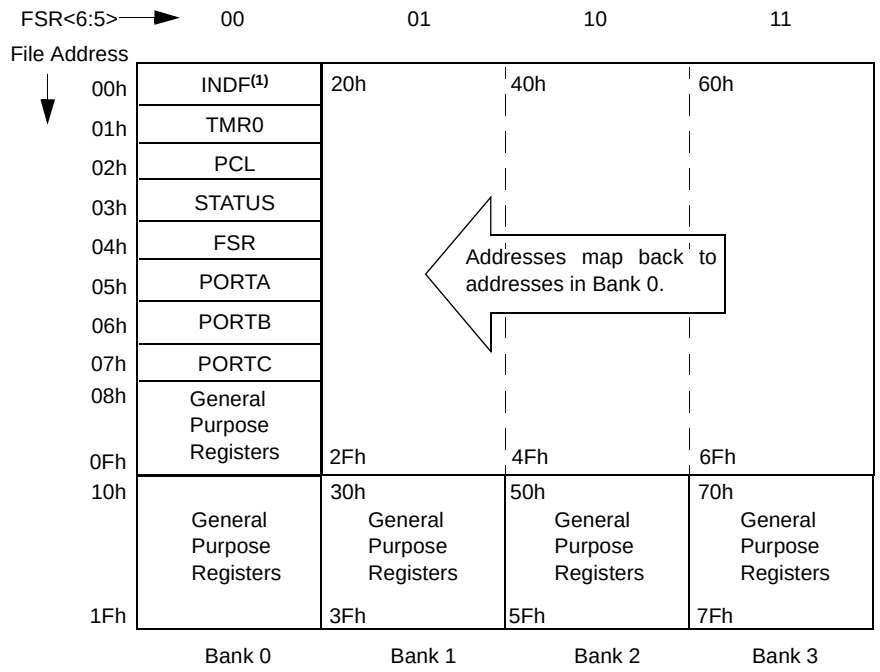
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

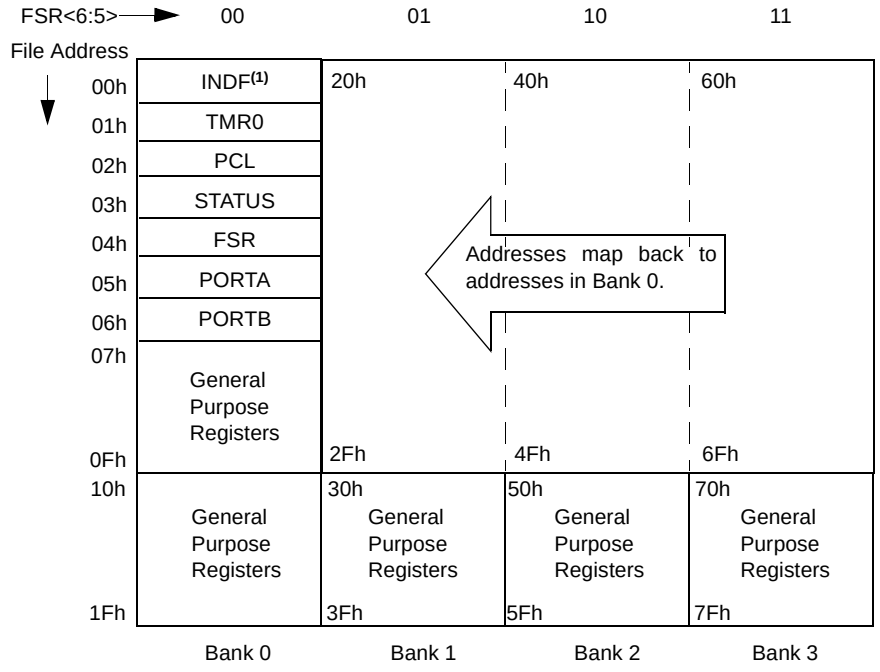
Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	12
Program Memory Size	3KB (2K x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	73 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c58b-04-ss

FIGURE 6-5: PIC16C57/CR57 REGISTER FILE MAP



Note 1: Not a physical register. See Section 6.7.

FIGURE 6-6: PIC16C58/CR58 REGISTER FILE MAP



Note 1: Not a physical register. See Section 6.7.

6.3 STATUS Register

This register contains the arithmetic status of the ALU, the RESET status and the page preselect bits for program memories larger than 512 words.

The STATUS Register can be the destination for any instruction, as with any other register. If the STATUS Register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{TO}$ and $\overline{PD}$ bits are not writable. Therefore, the result of an instruction with the STATUS Register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper three bits and set the Z bit. This leaves the STATUS Register as `000u u1uu` (where `u` = unchanged).

It is recommended, therefore, that only `BCF`, `BSF` and `MOVWF` instructions be used to alter the STATUS Register because these instructions do not affect the Z, DC or C bits from the STATUS Register. For other instructions which do affect STATUS Bits, see Section 10.0, Instruction Set Summary.

REGISTER 6-1: STATUS REGISTER (ADDRESS: 03h)

R/W-0	R/W-0	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
PA2	PA1	PA0	$\overline{TO}$	$\overline{PD}$	Z	DC	C
bit 7							bit 0

bit 7: **PA2**: This bit unused at this time.
Use of the PA2 bit as a general purpose read/write bit is not recommended, since this may affect upward compatibility with future products.

bit 6-5: **PA<1:0>**: Program page preselect bits (PIC16C56/CR56)(PIC16C57/CR57)(PIC16C58/CR58)
`00` = Page 0 (000h - 1FFh) - PIC16C56/CR56, PIC16C57/CR57, PIC16C58/CR58
`01` = Page 1 (200h - 3FFh) - PIC16C56/CR56, PIC16C57/CR57, PIC16C58/CR58
`10` = Page 2 (400h - 5FFh) - PIC16C57/CR57, PIC16C58/CR58
`11` = Page 3 (600h - 7FFh) - PIC16C57/CR57, PIC16C58/CR58
Each page is 512 words.
Using the PA<1:0> bits as general purpose read/write bits in devices which do not use them for program page preselect is not recommended since this may affect upward compatibility with future products.

bit 4: **$\overline{TO}$**: Time-out bit
`1` = After power-up, `CLRWDT` instruction, or `SLEEP` instruction
`0` = A WDT time-out occurred

bit 3: **$\overline{PD}$**: Power-down bit
`1` = After power-up or by the `CLRWDT` instruction
`0` = By execution of the `SLEEP` instruction

bit 2: **Z**: Zero bit
`1` = The result of an arithmetic or logic operation is zero
`0` = The result of an arithmetic or logic operation is not zero

bit 1: **DC**: Digit carry/$\overline{borrow}$ bit (for `ADDWF` and `SUBWF` instructions)
ADDWF
`1` = A carry from the 4th low order bit of the result occurred
`0` = A carry from the 4th low order bit of the result did not occur
SUBWF
`1` = A borrow from the 4th low order bit of the result did not occur
`0` = A borrow from the 4th low order bit of the result occurred

bit 0: **C**: Carry/$\overline{borrow}$ bit (for `ADDWF`, `SUBWF` and `RRF`, `RLF` instructions)

ADDWF	SUBWF	RRF or RLF
`1` = A carry occurred	`1` = A borrow did not occur	Loaded with LSb or MSb, respectively
`0` = A carry did not occur	`0` = A borrow occurred	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	1 = bit is set	0 = bit is cleared	x = bit is unknown

NOTES:

NOTES:

9.0 SPECIAL FEATURES OF THE CPU

What sets a microcontroller apart from other processors are special circuits that deal with the needs of real-time applications. The PIC16C5X family of microcontrollers have a host of such features intended to maximize system reliability, minimize cost through elimination of external components, provide power saving operating modes and offer code protection. These features are:

- Oscillator Selection (Section 4.0)
- RESET (Section 5.0)
- Power-On Reset (Section 5.1)
- Device Reset Timer (Section 5.2)
- Watchdog Timer (WDT) (Section 9.2)
- SLEEP (Section 9.3)
- Code protection (Section 9.4)
- ID locations (Section 9.5)

The PIC16C5X Family has a Watchdog Timer which can be shut off only through configuration bit WDTE. It runs off of its own RC oscillator for added reliability. There is an 18 ms delay provided by the Device Reset Timer (DRT), intended to keep the chip in RESET until the crystal oscillator is stable. With this timer on-chip, most applications need no external RESET circuitry.

The SLEEP mode is designed to offer a very low current Power-down mode. The user can wake up from SLEEP through external RESET or through a Watchdog Timer time-out. Several oscillator options are also made available to allow the part to fit the application. The RC oscillator option saves system cost while the LP crystal option saves power. A set of configuration bits are used to select various options.

12.6 Timing Parameter Symbology and Load Conditions

The timing parameter symbols have been created with one of the following formats:

1. TppS2ppS
2. TppS

T	
F Frequency	T Time

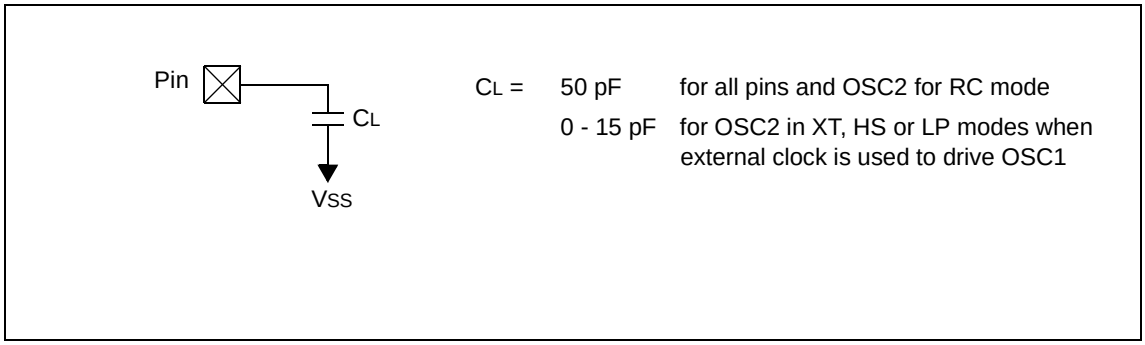
Lowercase letters (pp) and their meanings:

pp	
2 to	mc $\overline{\text{MCLR}}$
ck CLKOUT	osc oscillator
cy cycle time	os OSC1
drt device reset timer	t0 T0CKI
io I/O port	wdt watchdog timer

Uppercase letters and their meanings:

S	
F Fall	P Period
H High	R Rise
I Invalid (Hi-impedance)	V Valid
L Low	Z Hi-impedance

FIGURE 12-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS - PIC16C54/55/56/57



13.1 DC Characteristics: PIC16CR54A-04, 10, 20, PIC16LCR54A-04 (Commercial) PIC16CR54A-04I, 10I, 20I, PIC16LCR54A-04I (Industrial)

PIC16LCR54A-04 **PIC16LCR54A-04I** (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
PIC16CR54A-04, 10, 20 **PIC16CR54A-04I, 10I, 20I** (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
Param No.	**Symbol**	**Characteristic/Device**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VDD	**Supply Voltage**					
D001		PIC16LCR54A	2.0	—	6.25	V	
D001 D001A		PIC16CR54A	2.5 4.5	— —	6.25 5.5	V V	RC and XT modes HS mode
D002	VDR	**RAM Data Retention Voltage(1)**	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	VSS	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
	IDD	**Supply Current(2)**					
D005		PICLCR54A	— —	10 —	20 70	µA µA	Fosc = 32 kHz, VDD = 2.0V Fosc = 32 kHz, VDD = 6.0V
D005A		PIC16CR54A					**RC(3) and XT modes:**
			— — —	2.0 0.8 90	3.6 1.8 350	mA mA µA	FOSC = 4.0 MHz, VDD = 6.0V FOSC = 4.0 MHz, VDD = 3.0V FOSC = 200 kHz, VDD = 2.5V
							HS mode:
			— —	4.8 9.0	10 20	mA mA	FOSC = 10 MHz, VDD = 5.5V FOSC = 20 MHz, VDD = 5.5V

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

FIGURE 14-21: PORTA, B AND C I_{OL} vs. V_{OL}, V_{DD} = 3 V

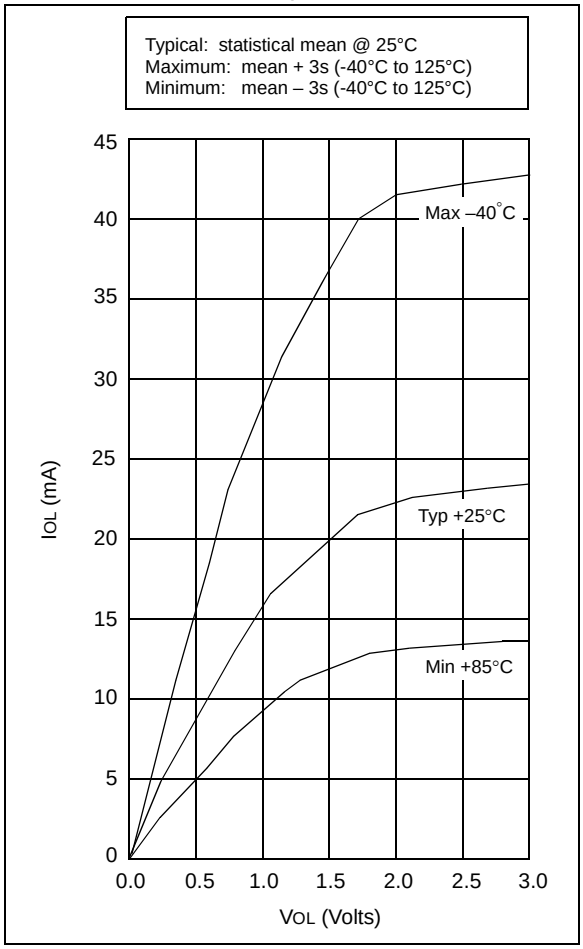
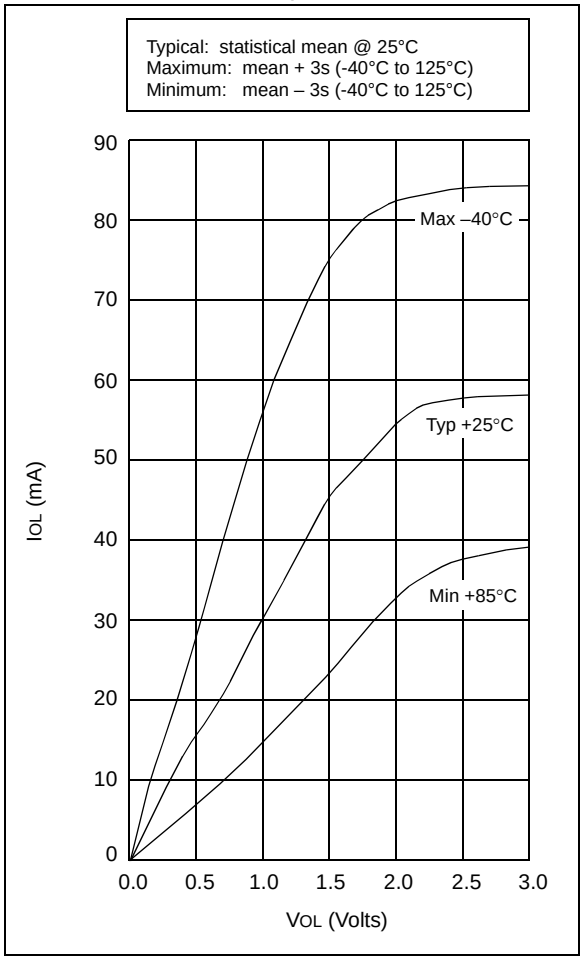


FIGURE 14-22: PORTA, B AND C I_{OL} vs. V_{OL}, V_{DD} = 5 V



15.0 ELECTRICAL CHARACTERISTICS - PIC16C54A

Absolute Maximum Ratings(†)

Ambient temperature under bias ..... –55°C to +125°C
Storage temperature ..... –65°C to +150°C
Voltage on V_{DD} with respect to V_{SS} ..... 0 to +7.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} ..... 0 to +14V
Voltage on all other pins with respect to V_{SS} ..... –0.6V to (V_{DD} + 0.6V)
Total power dissipation(1) ..... 800 mW
Max. current out of V_{SS} pin ..... 150 mA
Max. current into V_{DD} pin ..... 100 mA
Max. current into an input pin (T0CKI only) ..... ±500 µA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ±20 mA
Max. output current sunk by any I/O pin ..... 25 mA
Max. output current sourced by any I/O pin ..... 20 mA
Max. output current sourced by a single I/O port (PORTA or B) ..... 50 mA
Max. output current sunk by a single I/O port (PORTA or B) ..... 50 mA

Note 1: Power dissipation is calculated as follows: $Pdis = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

† NOTICE: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

15.2 DC Characteristics: PIC16C54A-04E, 10E, 20E (Extended) PIC16LC54A-04E (Extended)

PIC16LC54A-04E (Extended)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature –40°C ≤ TA ≤ +125°C for extended				
PIC16C54A-04E, 10E, 20E (Extended)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VDD	**Supply Voltage**					
D001		PIC16LC54A	3.0 2.5	— —	6.25 6.25	V V	XT and RC modes LP mode
D001A		PIC16C54A	3.5 4.5	— —	5.5 5.5	V V	RC and XT modes HS mode
D002	VDR	**RAM Data Retention Voltage(1)**	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
	IDD	**Supply Current(2)**					
D010		PIC16LC54A	—	0.5	25	mA	FOSC = 4.0 MHz, VDD = 5.5V, RC(3) and XT modes
			—	11	27	µA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Commercial
			—	11	35	µA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Industrial
			—	11	37	µA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Extended
D010A		PIC16C54A	—	1.8	3.3	mA	FOSC = 4.0 MHz, VDD = 5.5V, RC(3) and XT modes
			—	4.8	10	mA	FOSC = 10 MHz, VDD = 5.5V, HS mode
			—	9.0	20	mA	FOSC = 20 MHz, VDD = 5.5V, HS mode

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

15.4 DC Characteristics: PIC16C54A-04, 10, 20, PIC16LC54A-04, PIC16LV54A-02 (Commercial) PIC16C54A-04I, 10I, 20I, PIC16LC54A-04I, PIC16LV54A-02I (Industrial) PIC16C54A-04E, 10E, 20E, PIC16LC54A-04E (Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial –20°C ≤ TA ≤ +85°C for industrial-PIC16LV54A-02I –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D030	VIL	**Input Low Voltage**					
		I/O ports	VSS	—	0.2 VDD	V	Pin at hi-impedance
		MCLR (Schmitt Trigger)	VSS	—	0.15 VDD	V	
		T0CKI (Schmitt Trigger)	VSS	—	0.15 VDD	V	
		OSC1 (Schmitt Trigger)	VSS	—	0.15 VDD	V	RC mode only(3)
		OSC1	VSS	—	0.3 VDD		XT, HS and LP modes
D040	VIH	**Input High Voltage**					
		I/O ports	0.2 VDD + 1	—	VDD	V	For all VDD(4)
		I/O ports	2.0	—	VDD	V	4.0V < VDD ≤ 5.5V(4)
		MCLR (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		T0CKI (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		OSC1 (Schmitt Trigger)	0.85 VDD	—	VDD	V	RC mode only(3)
		OSC1	0.7 VDD	—	VDD	V	XT, HS and LP modes
D050	VHYS	**Hysteresis of Schmitt Trigger inputs**	0.15 VDD*	—	—	V	
D060	IIL	**Input Leakage Current(1,2)**					**For VDD ≤ 5.5V:**
		I/O ports	-1.0	0.5	+1.0	µA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
		MCLR	-5.0	—	+5.0	µA	VPIN = VSS +0.25V
		MCLR	—	0.5	+3.0	µA	VPIN = VDD
		T0CKI	-3.0	0.5	+3.0	µA	VSS ≤ VPIN ≤ VDD
		OSC1	-3.0	0.5	—	µA	VSS ≤ VPIN ≤ VDD, XT, HS and LP modes
D080	VOL	**Output Low Voltage**					
		I/O ports	—	—	0.6	V	IOL = 8.7 mA, VDD = 4.5V
		OSC2/CLKOUT	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, RC mode only
	VOH	**Output High Voltage(2)**					
		I/O ports	VDD - 0.7	—	—	V	IOH = -5.4 mA, VDD = 4.5V
		OSC2/CLKOUT	VDD - 0.7	—	—	V	IOH = -1.0 mA, VDD = 4.5V, RC mode only

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

2: Negative current is defined as coming out of the pin.

3: For the RC mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

FIGURE 16-14: TYPICAL IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 300 pF, 25°C)

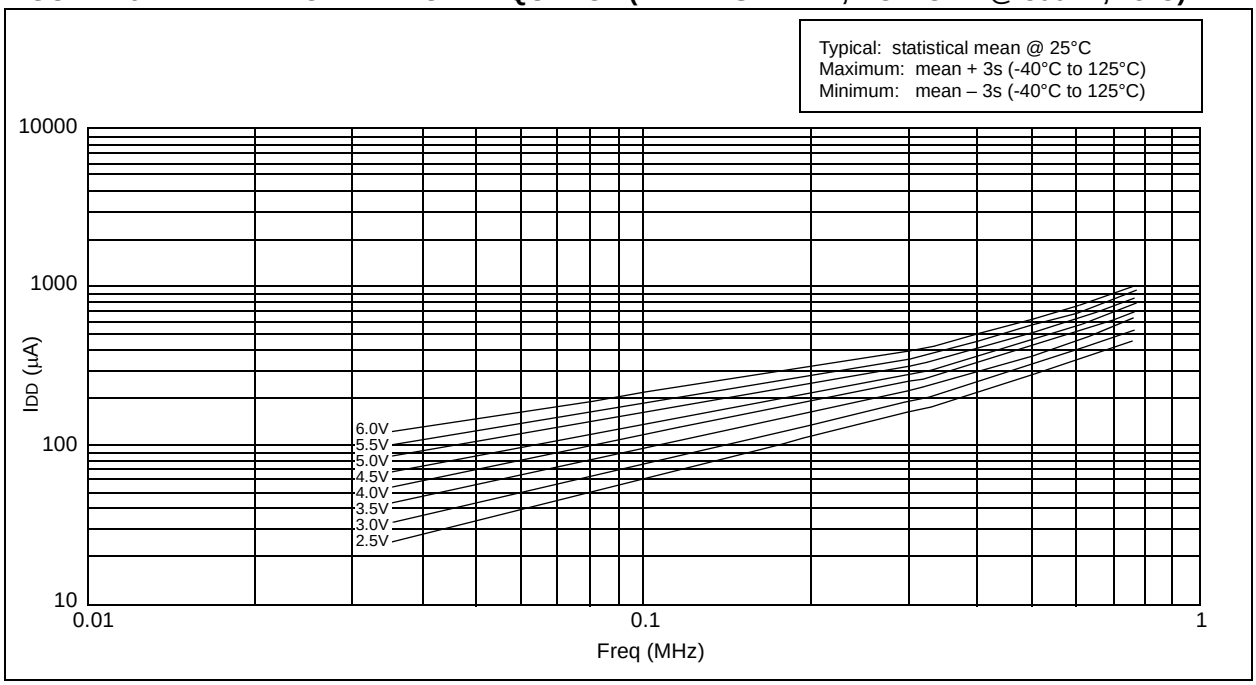
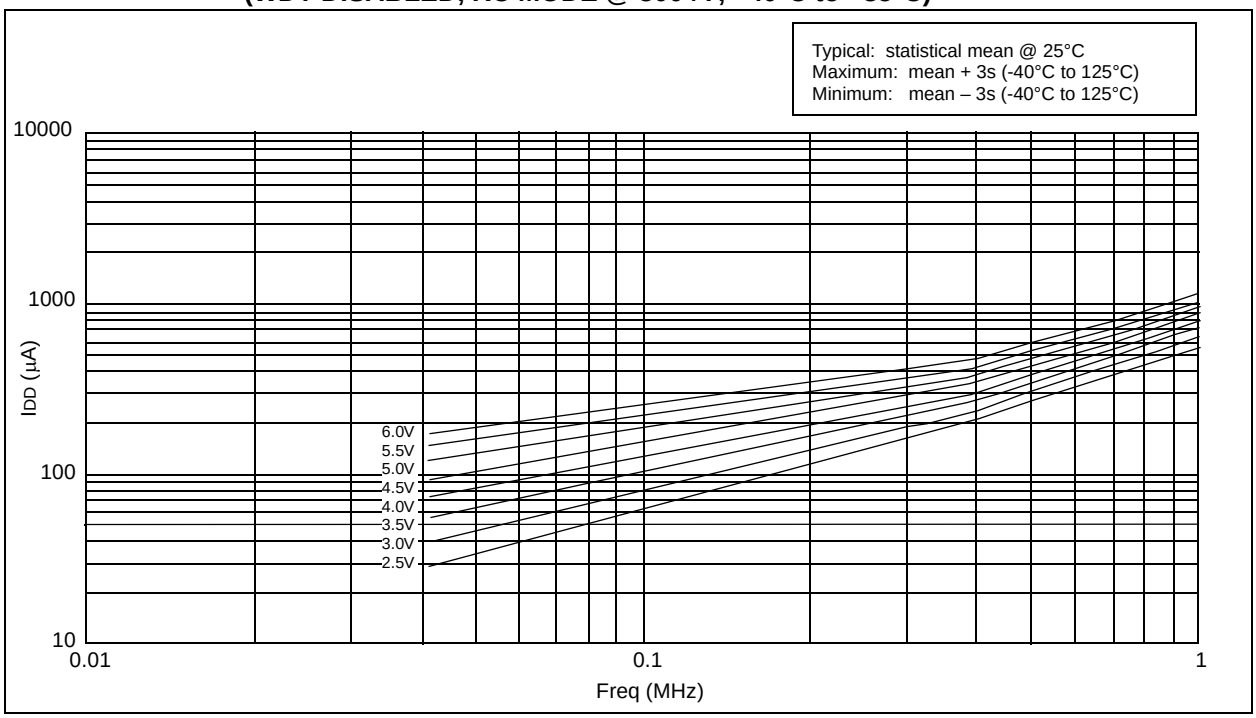


FIGURE 16-15: MAXIMUM IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 300 pF, –40°C to +85°C)



17.1 DC Characteristics: PIC16C54C/C55A/C56A/C57C/C58B-04, 20 (Commercial, Industrial) PIC16LC54C/LC55A/LC56A/LC57C/LC58B-04 (Commercial, Industrial) PIC16CR54C/CR56A/CR57C/CR58B-04, 20 (Commercial, Industrial) PIC16LCR54C/LCR56A/LCR57C/LCR58B-04 (Commercial, Industrial)

PIC16LC5X **PIC16LCR5X** (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
PIC16C5X **PIC16CR5X** (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
Param No.	**Symbol**	**Characteristic/Device**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	IPD	**Power-down Current(2)**					
D020		PIC16LC5X	—	0.25	2	µA	VDD = 2.5V, WDT disabled, Commercial
			—	0.25	3	µA	VDD = 2.5V, WDT disabled, Industrial
			—	1	5	µA	VDD = 2.5V, WDT enabled, Commercial
			—	1.25	8	µA	VDD = 2.5V, WDT enabled, Industrial
D020A		PIC16C5X	—	0.25	4.0	µA	VDD = 3.0V, WDT disabled, Commercial
			—	0.25	5.0	µA	VDD = 3.0V, WDT disabled, Industrial
			—	1.8	7.0*	µA	VDD = 5.5V, WDT disabled, Commercial
			—	2.0	8.0*	µA	VDD = 5.5V, WDT disabled, Industrial
			—	4	12*	µA	VDD = 3.0V, WDT enabled, Commercial
			—	4	14*	µA	VDD = 3.0V, WDT enabled, Industrial
			—	9.8	27*	µA	VDD = 5.5V, WDT enabled, Commercial
			—	12	30*	µA	VDD = 5.5V, WDT enabled, Industrial

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

17.3 DC Characteristics: PIC16C54C/C55A/C56A/C57C/C58B-04, 20 (Commercial, Industrial, Extended) PIC16LC54C/LC55A/LC56A/LC57C/LC58B-04 (Commercial, Industrial) PIC16CR54C/CR56A/CR57C/CR58B-04, 20 (Commercial, Industrial, Extended) PIC16LCR54C/LCR56A/LCR57C/LCR58B-04 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D030	VIL	**Input Low Voltage**					
		I/O Ports	VSS	—	0.8 V	V	4.5V <VDD ≤ 5.5V
		I/O Ports	VSS	—	0.15 VDD	V	Otherwise
		$\overline{\text{MCLR}}$ (Schmitt Trigger)	VSS	—	0.15 VDD	V	
		T0CKI (Schmitt Trigger)	VSS	—	0.15 VDD	V	
		OSC1 (Schmitt Trigger)	VSS	—	0.15 VDD	V	RC mode only(3)
		OSC1	VSS	—	0.3 VDD	V	XT, HS and LP modes
D040	VIH	**Input High Voltage**					
		I/O ports	2.0	—	VDD	V	4.5V < VDD ≤ 5.5V
		I/O ports	0.25 VDD+0.8	—	VDD	V	Otherwise
		$\overline{\text{MCLR}}$ (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		T0CKI (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		OSC1 (Schmitt Trigger)	0.85 VDD	—	VDD	V	RC mode only(3)
		OSC1	0.7 VDD	—	VDD	V	XT, HS and LP modes
D050	VHYS	**Hysteresis of Schmitt Trigger inputs**	0.15 VDD*	—	—	V	
D060	IIL	**Input Leakage Current(1,2)**					**For VDD ≤ 5.5V:**
		I/O ports	-1.0	0.5	+1.0	µA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
		$\overline{\text{MCLR}}$	-5.0	—	+5.0	µA	VPIN = VSS +0.25V
		$\overline{\text{MCLR}}$		0.5	+3.0	µA	VPIN = VDD
		T0CKI	-3.0	0.5	+3.0	µA	VSS ≤ VPIN ≤ VDD
		OSC1	-3.0	0.5	—	µA	VSS ≤ VPIN ≤ VDD, XT, HS and LP modes
D080	VOL	**Output Low Voltage**					
		I/O ports	—	—	0.6	V	IOL = 8.7 mA, VDD = 4.5V
		OSC2/CLKOUT	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, RC mode only
D090	VOH	**Output High Voltage(2)**					
		I/O ports	VDD - 0.7	—	—	V	IOH = -5.4 mA, VDD = 4.5V
		OSC2/CLKOUT	VDD - 0.7	—	—	V	IOH = -1.0 mA, VDD = 4.5V, RC mode only

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the $\overline{\text{MCLR}}$/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

2: Negative current is defined as coming out of the pin.

3: For the RC mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

18.0 DEVICE CHARACTERIZATION - PIC16LC54A

The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

"Typical" represents the mean of the distribution at 25°C. "Maximum" or "minimum" represents (mean + 3σ) or (mean – 3σ) respectively, where σ is a standard deviation, over the whole temperature range.

FIGURE 18-1: TYPICAL RC OSCILLATOR FREQUENCY vs. TEMPERATURE

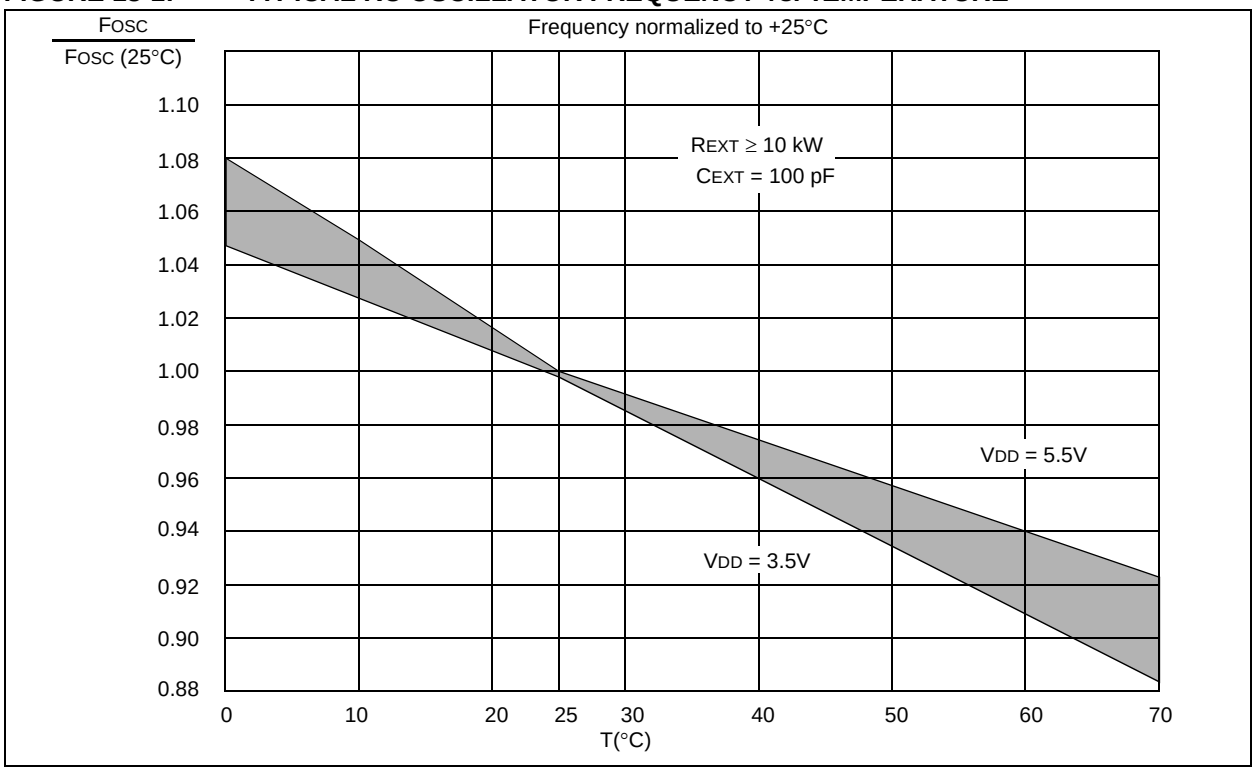


TABLE 18-1: RC OSCILLATOR FREQUENCIES

CEXT	REXT	Average Fosc @ 5V, 25°C	
20 pF	3.3K	5 MHz	± 27%
	5K	3.8 MHz	± 21%
	10K	2.2 MHz	± 21%
	100K	262 kHz	± 31%
100 pF	3.3K	1.63 MHz	± 13%
	5K	1.2 MHz	± 13%
	10K	684 kHz	± 18%
	100K	71 kHz	± 25%
300 pF	3.3K	660 kHz	± 10%
	5.0K	484 kHz	± 14%
	10K	267 kHz	± 15%
	100K	29 kHz	± 19%

The frequencies are measured on DIP packages.

The percentage variation indicated here is part-to-part variation due to normal process distribution. The variation indicated is ±3 standard deviation from average value for VDD = 5V.

FIGURE 18-6: TYPICAL IPD vs. VDD, WATCHDOG ENABLED (25°C)

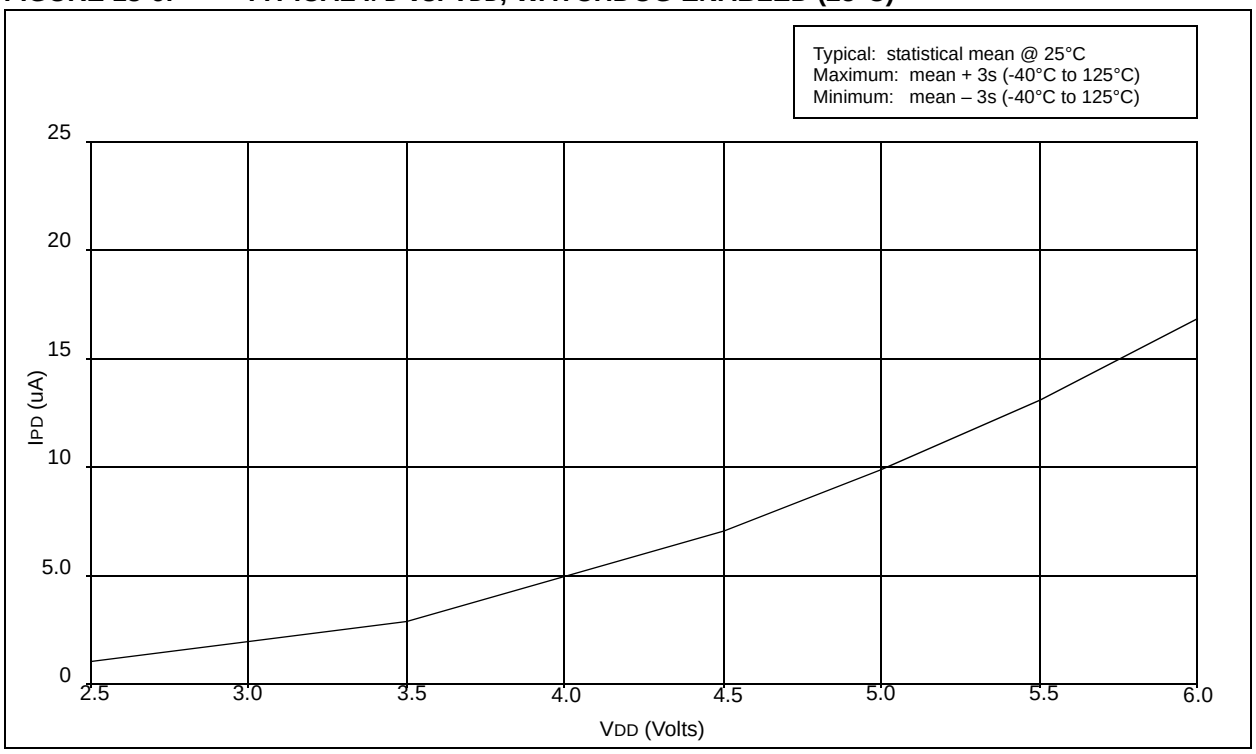


FIGURE 18-7: TYPICAL IPD vs. VDD, WATCHDOG ENABLED (–40°C, 85°C)

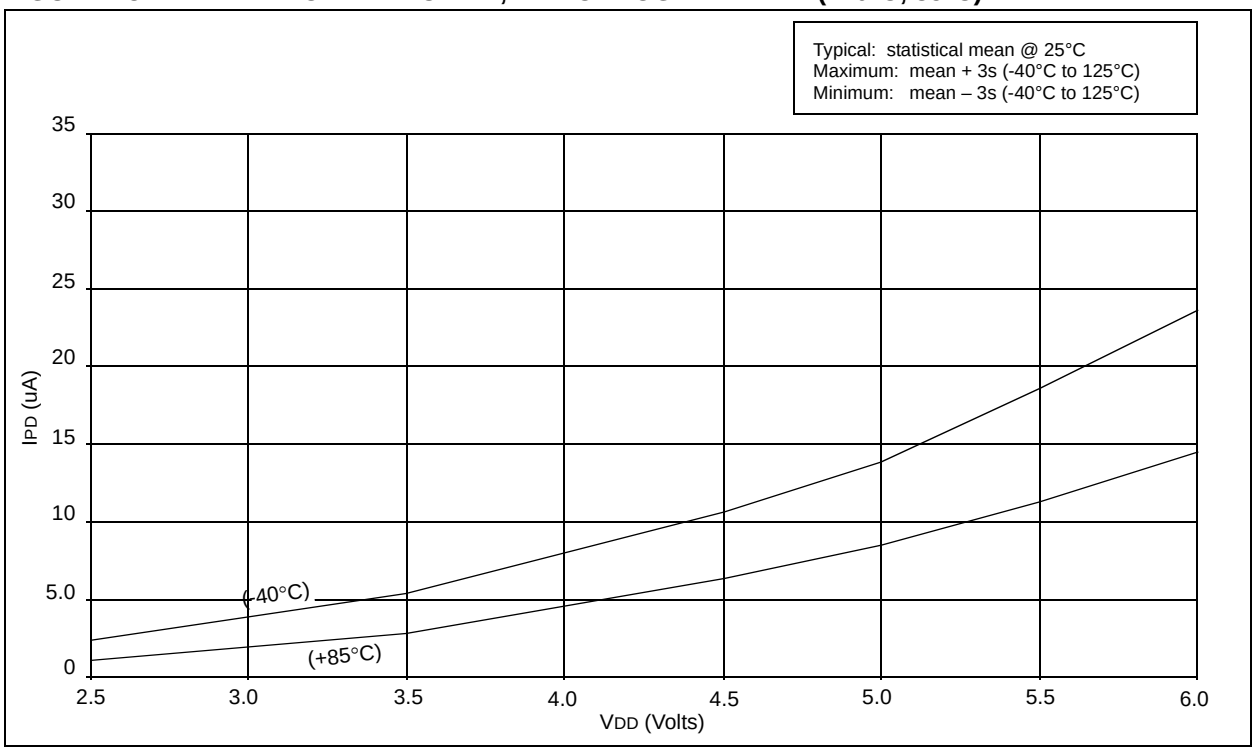


FIGURE 18-10: V_{TH} (INPUT THRESHOLD TRIP POINT VOLTAGE) OF OSC1 INPUT (IN XT, HS AND LP MODES) vs. V_{DD}

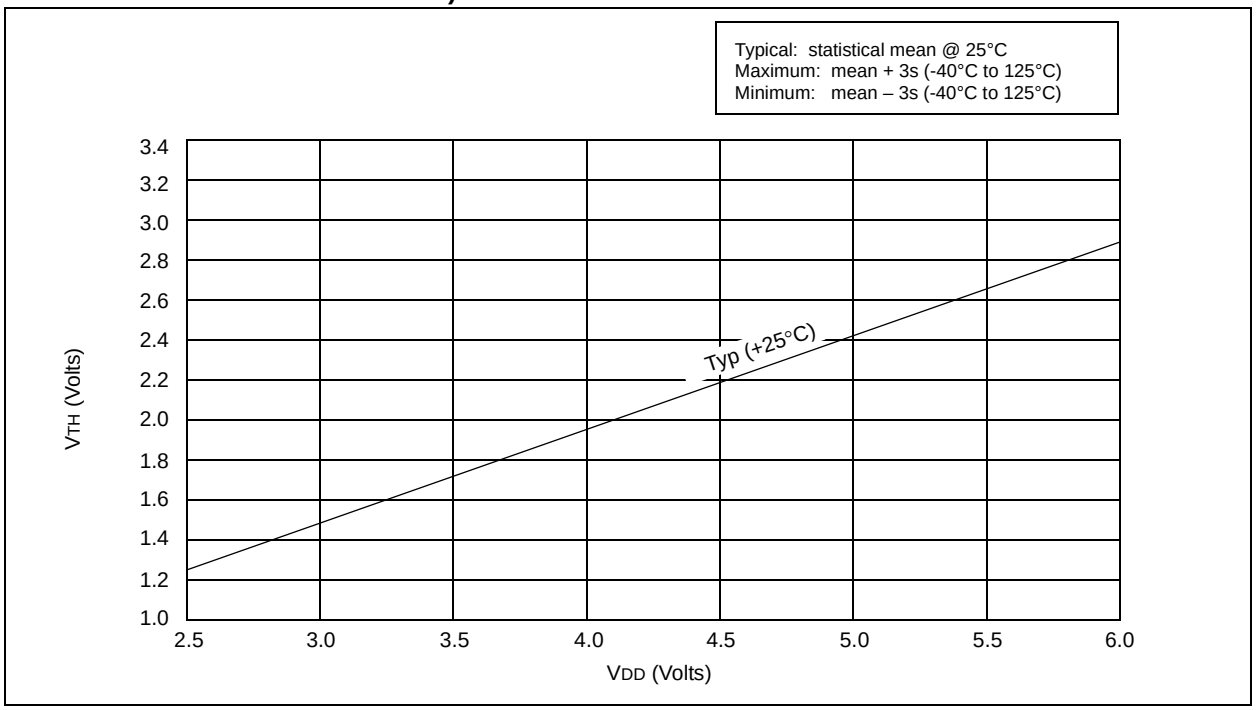
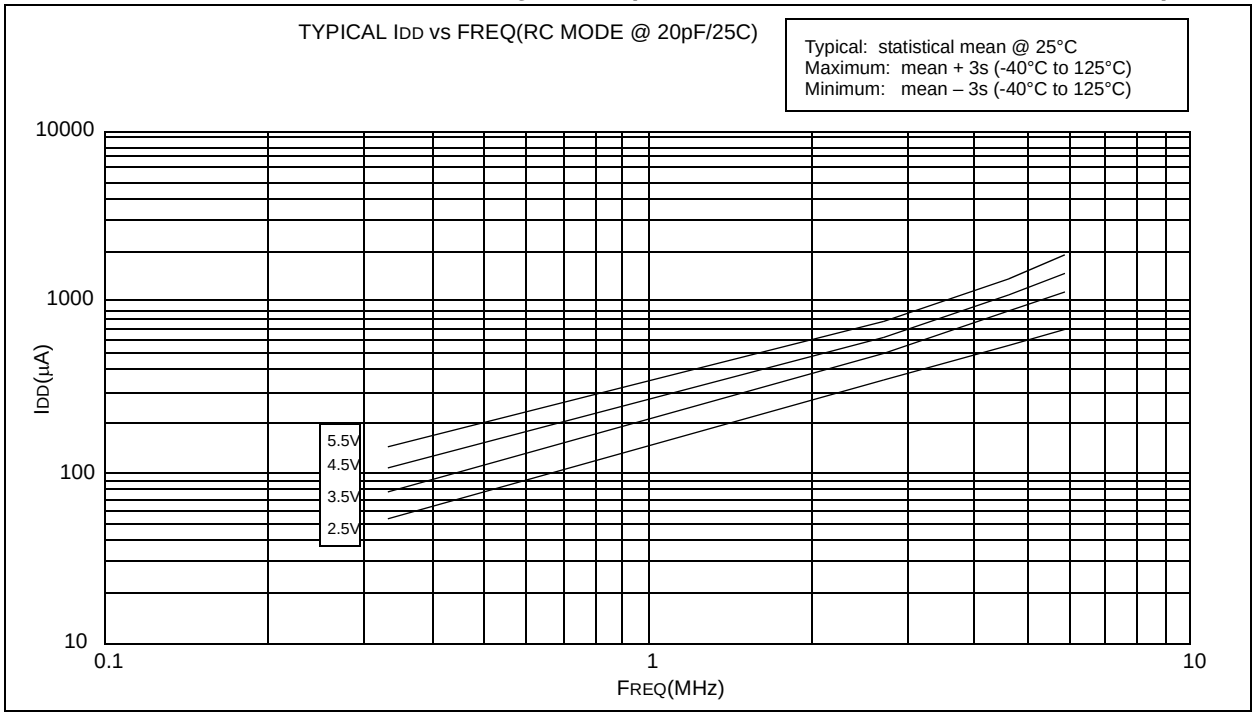


FIGURE 18-11: TYPICAL I_{DD} vs. FREQUENCY (WDT DISABLED, RC MODE @ 20 pF, 25°C)



19.2 DC Characteristics: PIC16C54C/C55A/C56A/C57C/C58B-40 (Commercial)(1)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D030	VIL	**Input Low Voltage**					
		I/O Ports	VSS	—	0.8	V	4.5V <VDD ≤ 5.5V
		MCLR (Schmitt Trigger)	VSS	—	0.15 VDD	V	
		T0CKI (Schmitt Trigger)	VSS	—	0.15 VDD	V	
		OSC1	VSS	—	0.2 VDD	V	HS, 20 MHz ≤ FOSC ≤ 40 MHz
D040	VIH	**Input High Voltage**					
		I/O ports	2.0	—	VDD	V	4.5V < VDD ≤ 5.5V
		MCLR (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		T0CKI (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		OSC1	0.8 VDD	—	VDD	V	HS, 20 MHz ≤ FOSC ≤ 40 MHz
D050	VHYS	**Hysteresis of Schmitt Trigger inputs**	0.15 VDD*	—	—	V	
D060	IIL	**Input Leakage Current(2,3)**					**For VDD ≤ 5.5V:**
		I/O ports	-1.0	0.5	+1.0	µA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
		MCLR	-5.0	—	+5.0	µA	VPIN = VSS +0.25V
		MCLR	—	0.5	+3.0	µA	VPIN = VDD
		T0CKI	-3.0	0.5	+3.0	µA	VSS ≤ VPIN ≤ VDD
		OSC1	-3.0	0.5	—	µA	VSS ≤ VPIN ≤ VDD, HS
D080	VOL	**Output Low Voltage**					
		I/O ports	—	—	0.6	V	IOL = 8.7 mA, VDD = 4.5V
D090	VOH	**Output High Voltage(3)**					
		I/O ports	VDD - 0.7	—	—	V	IOH = -5.4 mA, VDD = 4.5V

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: Device operation between 20 MHz to 40 MHz requires the following: VDD between 4.5V to 5.5V, OSC1 pin externally driven, OSC2 pin not connected and HS oscillator mode and commercial temperatures. For operation between DC and 20 MHz, See Section 17.3.

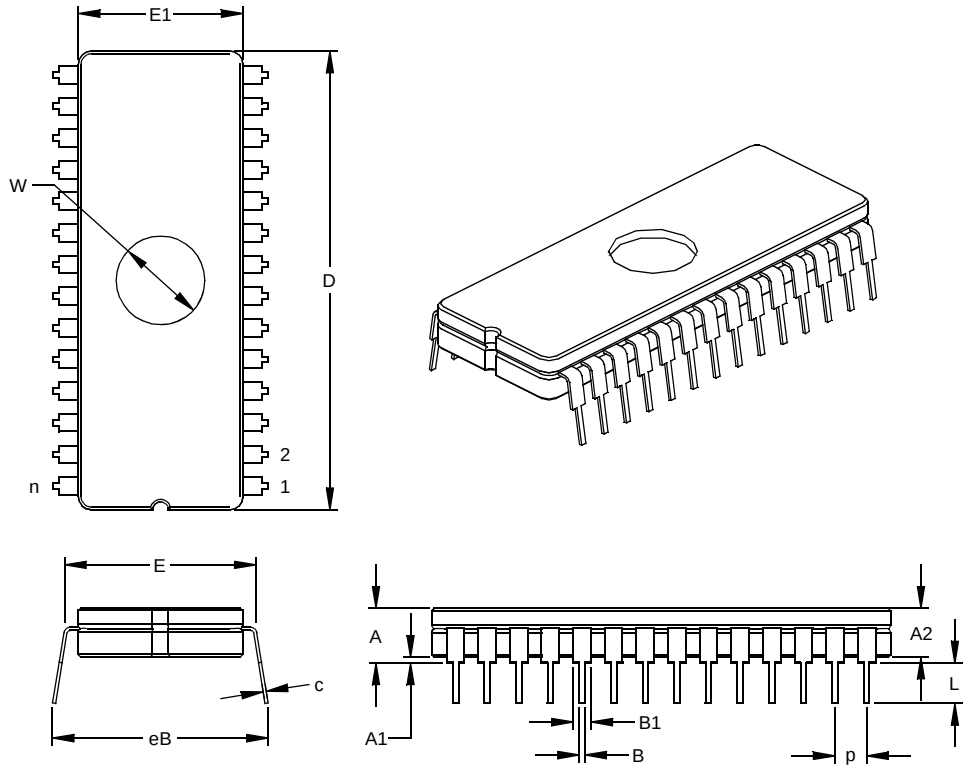
2: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

3: Negative current is defined as coming out of the pin.

NOTES:

28-Lead Ceramic Dual In-line with Window (JW) – 600 mil (CERDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.195	.210	.225	4.95	5.33	5.72
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.038	.060	0.38	0.95	1.52
Shoulder to Shoulder Width	E	.595	.600	.625	15.11	15.24	15.88
Ceramic Pkg. Width	E1	.514	.520	.526	13.06	13.21	13.36
Overall Length	D	1.430	1.460	1.490	36.32	37.08	37.85
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	c	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.058	.065	1.27	1.46	1.65
Lower Lead Width	B	.016	.020	.023	0.41	0.51	0.58
Overall Row Spacing §	eB	.610	.660	.710	15.49	16.76	18.03
Window Diameter	W	.270	.280	.290	6.86	7.11	7.37

* Controlling Parameter
§ Significant Characteristic
JEDEC Equivalent: MO-103
Drawing No. C04-013